2-103167-2 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 2-103167-2 PCB Mount Header, Right Angle, Wire-to-Board, 50 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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Connector System: Wire-to-Board

Number of Positions: **50**

Number of Rows: 2

Centerline (Pitch): 2.54 mm [.1 in]

PCB Mount Orientation: Right Angle

Features

Product Type Features

Connector SystemWire-to-BoardHeader TypeFully ShroudedConnector & Contact Terminates ToPrinted Circuit Board



PCB Mount Header

Configuration Features

Connector Contact Load Condition	Fully Loaded
Number of Positions	50
Number of Rows	2
PCB Mount Orientation	Right Angle
Electrical Characteristics	
Insulation Resistance	5000 ΜΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]

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Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.43 mm[.135 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
Mating Retention Type	Detent Window
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	Without
PCB Mount Retention	Without
Housing Features	
Housing Material	Thermoplastic
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
PCB Thickness (Recommended)	1.4 mm[.055 in]
Row-to-Row Spacing	2.54 mm[.1 in]
Usage Conditions	
Housing Temperature Rating	Standard
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal

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Industry Standards

Agency/Standard	CSA
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	32
Packaging Type	Tray
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Not Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2022 (224) SVHC > Threshold:

Pb (40% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after

handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Wave solder capable to 240°C

Product Compliance Disclaimer

Solder Process Capability

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

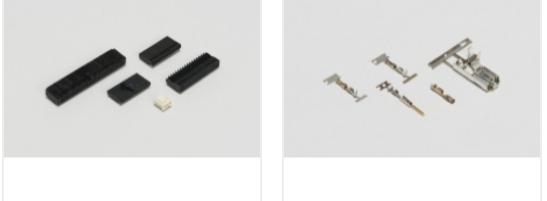
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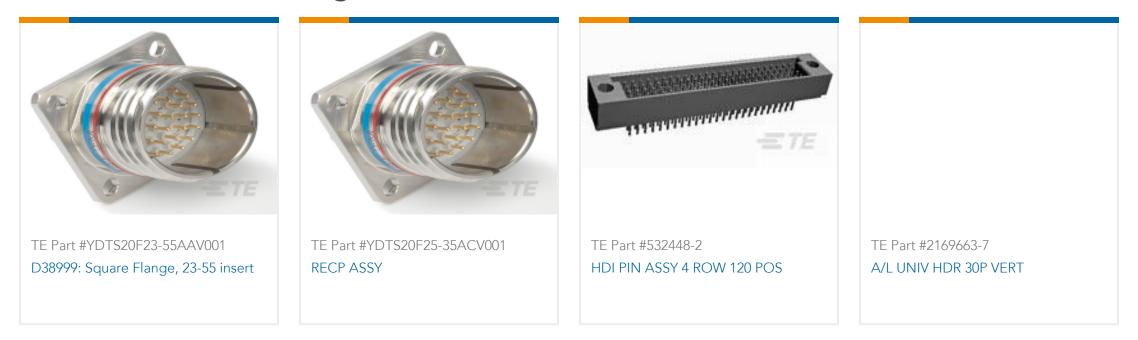
Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(65)
& Housings(5)	

Customers Also Bought





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Documents

Product Drawings 50 MODII HDR DRRA SHRD .100CL

English

CAD Files

Customer View Model ENG_CVM_CVM_2-103167-2_R.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2-103167-2_R.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2-103167-2_R.3d_stp.zip

English

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Product Specifications

Product Specification

English

Product Environmental Compliance

Product Compliance

English

Product Compliance

English